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With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

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Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China







IGBT

This Insulated Gate Bipolar Transistor (IGBT) features a robust and cost effective Trench construction, and provides superior performance in demanding switching applications, offering both low on state voltage and minimal switching loss. The IGBT is well suited for UPS and solar applications. Incorporated into the device is a soft and fast co–packaged free wheeling diode with a low forward voltage.

Features

- Low Saturation Voltage using Trench with Field Stop Technology
- Low Switching Loss Reduces System Power Dissipation
- 10 µs Short Circuit Capability
- Low Gate Charge
- Soft, Fast Free Wheeling Diode
- These are Pb-Free Devices

Typical Applications

- Solar Inverter
- UPS Inverter

ABSOLUTE MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Collector-emitter voltage	V _{CES}	1200	V
Collector current @ Tc = 25°C @ Tc = 100°C	Ŀc	30 15	А
Pulsed collector current, T _{pulse} limited by T _{Jmax}	I _{CM}	120	Α
Diode forward current @ Tc = 25°C @ Tc = 100°C	l _F	30 15	Α
Diode pulsed current, T _{pulse} limited by T _{Jmax}	I _{FM}	120	Α
Gate-emitter voltage	V_{GE}	±20	V
Power Dissipation @ Tc = 25°C @ Tc = 100°C	P _D	156 62.5	W
Short Circuit Withstand Time $V_{GE} = 15 \text{ V}, V_{CE} = 500 \text{ V}, T_J \le 150^{\circ}\text{C}$	T _{SC}	10	μs
Operating junction temperature range	TJ	–55 to +150	°C
Storage temperature range	T _{stg}	-55 to +150	°C
Lead temperature for soldering, 1/8" from case for 5 seconds	T _{SLD}	260	°C

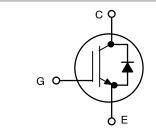
Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

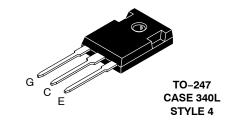


ON Semiconductor®

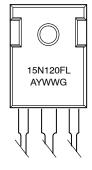
http://onsemi.com

15 A, 1200 V V_{CEsat} = 2.0 V E_{off} = 0.55 mJ





MARKING DIAGRAM



A = Assembly Location

Y = Year WW = Work Week G = Pb-Free Package

ORDERING INFORMATION

Device	Package	Shipping
NGTB15N120FLWG	TO-247 (Pb-Free)	30 Units / Rail

THERMAL CHARACTERISTICS

Rating	Symbol	Value	Unit
Thermal resistance junction-to-case, for IGBT	$R_{ heta JC}$	0.80	°C/W
Thermal resistance junction-to-case, for Diode	$R_{ heta JC}$	1.5	°C/W
Thermal resistance junction-to-ambient	$R_{ hetaJA}$	40	°C/W

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
STATIC CHARACTERISTIC	•	•	•	•		1
Collector-emitter breakdown voltage, gate-emitter short-circuited	V_{GE} = 0 V, I_{C} = 500 μA	V _{(BR)CES}	1200	_	-	V
Collector-emitter saturation voltage	V _{GE} = 15 V, I _C = 15 A V _{GE} = 15 V, I _C = 15 A, T _J = 150°C	V _{CEsat}	1.5 -	2.0 2.2	2.2	V
Gate-emitter threshold voltage	$V_{GE} = V_{CE}, I_{C} = 150 \mu A$	$V_{GE(th)}$	4.5	5.5	6.5	V
Collector-emitter cut-off current, gate- emitter short-circuited	V _{GE} = 0 V, V _{CE} = 1200 V V _{GE} = 0 V, V _{CE} = 1200 V, T _{J =} 150°C	I _{CES}	- -	- -	0.35 2	mA
Gate leakage current, collector-emitter short-circuited	V _{GE} = 20 V, V _{CE} = 0 V	I _{GES}	_	_	100	nA
DYNAMIC CHARACTERISTIC	•	•				•
Input capacitance		C _{ies}	_	3600	-	pF
Output capacitance	V _{CE} = 20 V, V _{GE} = 0 V, f = 1 MHz	C _{oes}	-	110	-	
Reverse transfer capacitance	7	C _{res}	_	66	-	
Gate charge total		Q_g	-	150	-	nC
Gate to emitter charge	V _{CE} = 600 V, I _C = 15 A, V _{GE} = 15 V	Q _{ge}	_	28	-	
Gate to collector charge	7	Q _{gc}	_	68	-	
SWITCHING CHARACTERISTIC, INDUC	TIVE LOAD					
Turn-on delay time		t _{d(on)}	_	72	-	ns
Rise time	7	t _r	_	19	-	
Turn-off delay time	T _J = 25°C	t _{d(off)}	_	168	-	
Fall time	$V_{CC} = 600 \text{ V}, I_{C} = 15 \text{ A}$ $R_{g} = 10 \Omega$	t _f	-	194	-	
Turn-on switching loss	V _{GE} = 0 V/ 15V	E _{on}	_	1.17	-	mJ
Turn-off switching loss		E _{off}	-	0.55	-	
Total switching loss	7	E _{ts}	_	1.72	-	
Turn-on delay time		t _{d(on)}	_	70	-	ns
Rise time	T _J = 125°C V _{CC} = 600 V, I _C = 15 A B ₋ = 10 Q	t _r	-	21	-	
Turn-off delay time		t _{d(off)}	_	175	-	
Fall time		t _f	_	310	-	
Turn-on switching loss	$R_g = 10 \Omega$ $V_{GE} = 0 V/ 15V$	E _{on}	-	1.35	-	mJ
Turn-off switching loss		E _{off}	-	0.96	-	
Total switching loss		E _{ts}	_	2.31	-	

ELECTRICAL CHARACTERISTICS ($T_J = 25^{\circ}C$ unless otherwise specified)

Parameter	Test Conditions	Symbol	Min	Тур	Max	Unit
DIODE CHARACTERISTIC						
Forward voltage	V _{GE} = 0 V, I _F = 15 A V _{GE} = 0 V, I _F = 15 A, T _J = 150°C	V _F	1.5	1.8 2.5	2.2	V
Reverse recovery time	T _J = 25°C	t _{rr}	-	166	_	ns
Reverse recovery charge	$I_F = 15 \text{ A}, V_R = 400 \text{ V}$ $di_F/dt = 200 \text{ A/}\mu\text{s}$	Q _{rr}	-	1.1	_	μс
Reverse recovery current		I _{rrm}	-	12	_	Α
Reverse recovery time	T _J = 125°C	t _{rr}	-	200	_	ns
Reverse recovery charge	I _F = 15 A, V _R = 400 V di _F /dt = 200 A/μs	Q _{rr}	-	1.5	-	μς
Reverse recovery current		I _{rrm}	_	15	_	Α

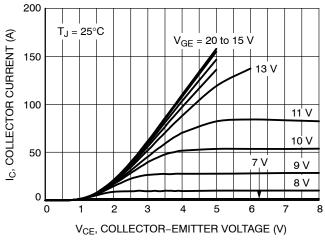


Figure 1. Output Characteristics

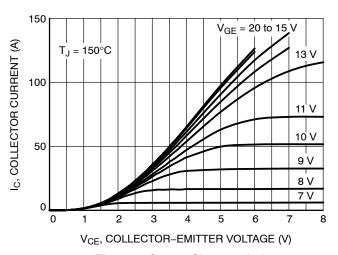


Figure 2. Output Characteristics

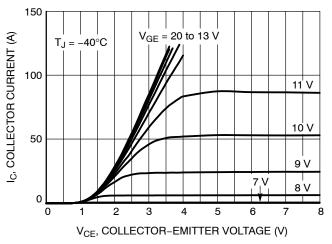


Figure 3. Output Characteristics

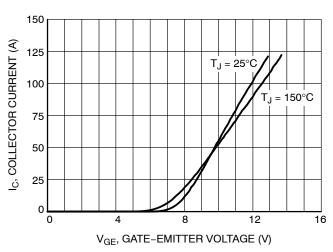


Figure 4. Typical Transfer Characteristics

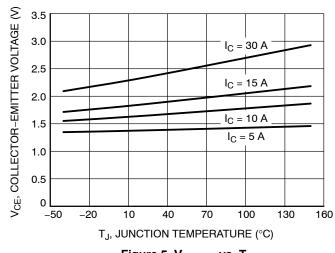


Figure 5. $V_{CE(sat)}$ vs. T_J

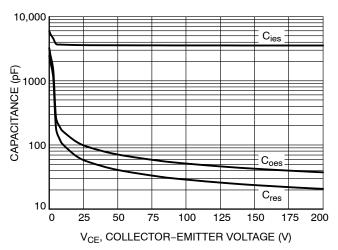


Figure 6. Typical Capacitance

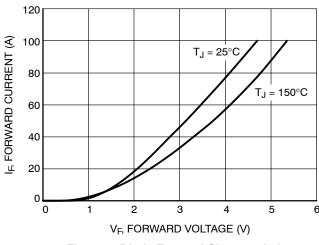


Figure 7. Diode Forward Characteristics

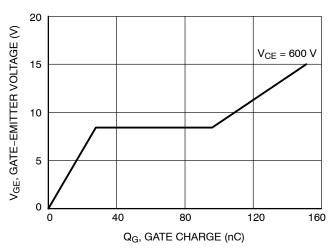


Figure 8. Typical Gate Charge

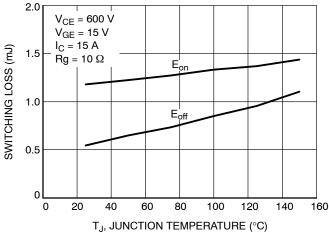


Figure 9. Switching Loss vs. Temperature

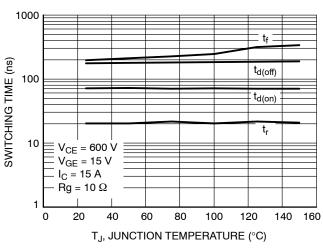


Figure 10. Switching Time vs. Temperature

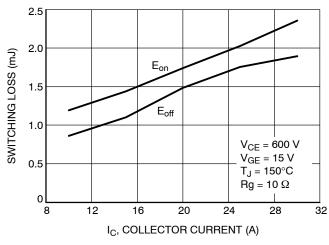


Figure 11. Switching Loss vs. I_C

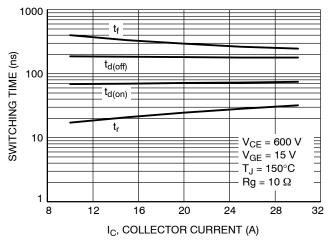
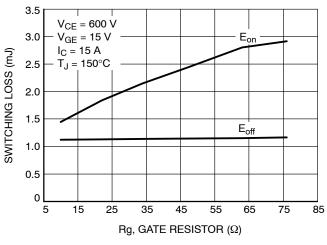


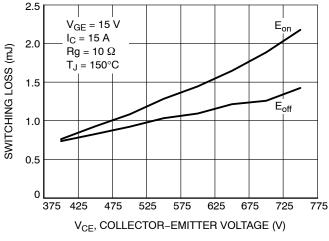
Figure 12. Switching Time vs. I_C



1000 t_{d(off)} t_{f} SWITCHING TIME (ns) $t_{d(on)}$ 100 : t_r 10 V_{CE} = 600 V V_{GE} = 15 V I_C = 15 A $T_{.1} = 150^{\circ}C$ 5 15 25 35 45 55 65 75 85 Rg, GATE RESISTOR (Ω)

Figure 13. Switching Loss vs. Rg

Figure 14. Switching Time vs. Rg



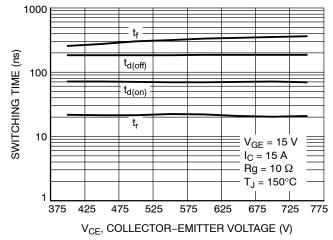
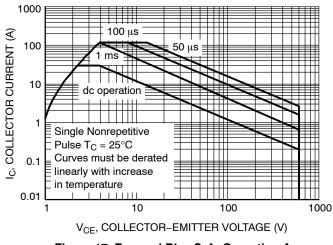


Figure 15. Switching Loss vs. V_{CE}

Figure 16. Switching Time vs. V_{CE}



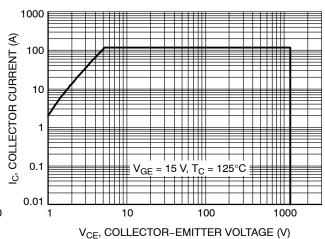


Figure 17. Forward Bias Safe Operating Area

Figure 18. Reverse Bias Safe Operating Area

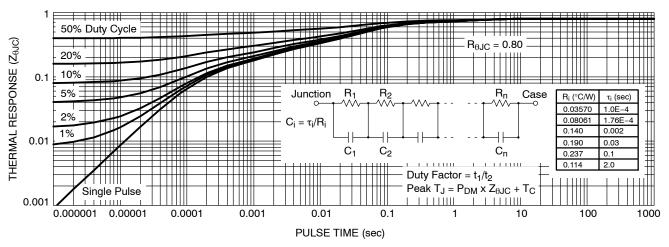


Figure 19. IGBT Transient Thermal Impedance

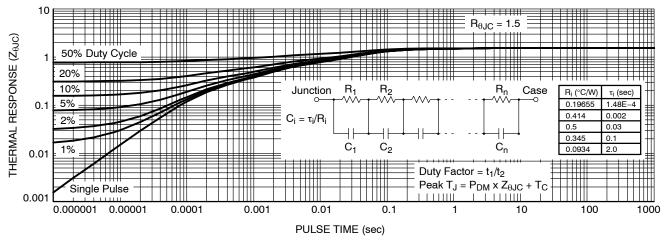


Figure 20. Diode Transient Thermal Impedance

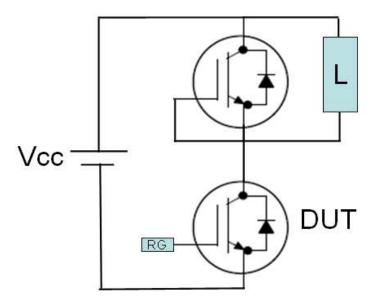


Figure 21. Test Circuit for Switching Characteristics

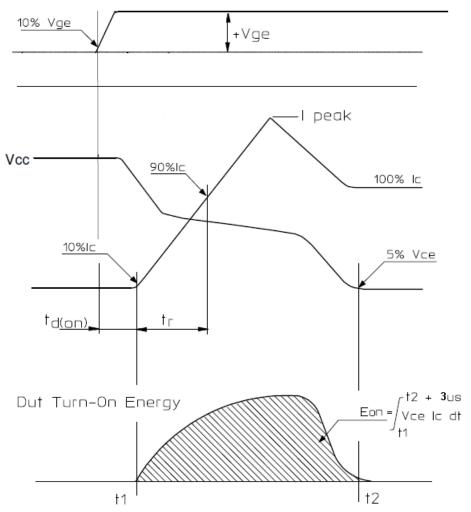


Figure 22. Definition of Turn On Waveform

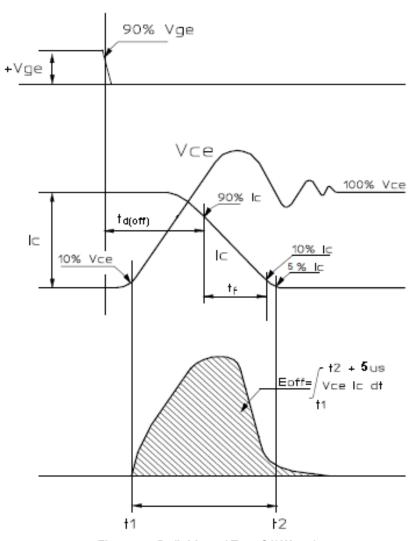
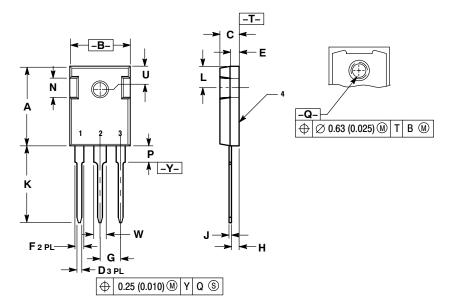


Figure 23. Definition of Turn Off Waveform

PACKAGE DIMENSIONS

TO-247 CASE 340L-02 ISSUE F



- DIMENSIONING AND TOLERANCING PER ANSI
- 2. CONTROLLING DIMENSION: MILLIMETER.

	MILLIMETERS		INCHES	
DIM	MIN	MAX	MIN	MAX
Α	20.32	21.08	0.800	8.30
В	15.75	16.26	0.620	0.640
С	4.70	5.30	0.185	0.209
D	1.00	1.40	0.040	0.055
Е	1.90	2.60	0.075	0.102
F	1.65	2.13	0.065	0.084
G	5.45	BSC	0.215	BSC
Н	1.50	2.49	0.059	0.098
J	0.40	0.80	0.016	0.031
K	19.81	20.83	0.780	0.820
L	5.40	6.20	0.212	0.244
N	4.32	5.49	0.170	0.216
Р		4.50		0.177
Q	3.55	3.65	0.140	0.144
U	6.15 BSC		0.242 BSC	
W	2.87	3.12	0.113	0.123

STYLE 4: PIN 1. GATE

- 2. COLLECTOR 3. EMITTER
- 4. COLLECTOR

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